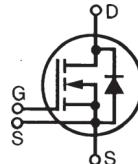


PolarHV™ HiPerFET Power MOSFET

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode

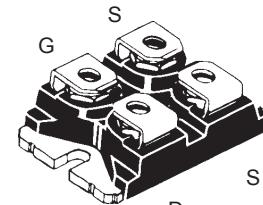
V_{DSS} = 500 V
 I_{D25} = 66 A
 $R_{DS(on)}$ ≤ 65 mΩ
 t_{rr} ≤ 200 ns



Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ C$ to $150^\circ C$	500		V
V_{DGR}	$T_J = 25^\circ C$ to $150^\circ C$; $R_{GS} = 1 M\Omega$	500		V
V_{GS}	Transient	± 40		V
V_{GSM}	Continuous	± 30		V
I_{D25}	$T_c = 25^\circ C$	66		A
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	200		A
I_{AR}	$T_c = 25^\circ C$	80		A
E_{AR}	$T_c = 25^\circ C$	80		mJ
E_{AS}	$T_c = 25^\circ C$	3.0		J
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100 A/\mu s$, $V_{DD} \leq V_{DSS}$, $T_j \leq 150^\circ C$, $R_G = 2 \Omega$	10		V/ns
P_D	$T_c = 25^\circ C$	700		W
T_J		-55 ... +150		°C
T_{JM}		150		°C
T_{stg}		-55 ... +150		°C
T_L	1.6 mm (0.062 in.) from case for 10 s	300		°C
V_{ISOL}	50/60 Hz; $I_{ISOL} \leq 1$ mA	2500		V~
M_d	Mounting torque Terminal connection torque (M4)	1.5/13	Nm/ib.in. 1.5/13	Nm/ib.in.
Weight		30		g

Symbol	Test Conditions ($T_j = 25^\circ C$ unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0 V$, $I_D = 500 \mu A$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 8$ mA	3.0		5.0 V
I_{GSS}	$V_{GS} = \pm 30 V_{DC}$, $V_{DS} = 0$		± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$		25	μA 1 mA
$R_{DS(on)}$	$V_{GS} = 10 V$, $I_D = 0.5 I_{D25}$, Note 1		65	mΩ

miniBLOC, SOT-227 B (IXFN)
 E153432



G = Gate
S = Source

Either source tab S can be used for source current or Kelvin gate return.

Features

- | Fast intrinsic diode
- | International standard package
- | Unclamped Inductive Switching (UIS) rated
- | UL recognized.
- | Isolated mounting base

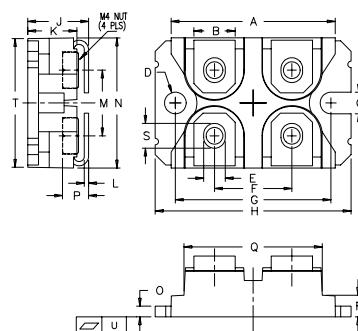
Advantages

- | Easy to mount
- | Space savings
- | High power density

Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ C$ unless otherwise specified)	Min.	Typ.	Max.
g_{fs}	$V_{DS} = 20 V$; $I_D = 0.5 I_{D25}$, Note 1	35	70	S	
C_{iss}			12.7	nF	
C_{oss}	$V_{GS} = 0 V$, $V_{DS} = 25 V$, $f = 1 MHz$		1280	pF	
C_{rss}			120	pF	
$t_{d(on)}$			25	ns	
t_r	$V_{GS} = 10 V$, $V_{DS} = 0.5 V_{DSS}$, $I_D = 0.5 * I_{D25}$		27	ns	
$t_{d(off)}$	$R_G = 2 \Omega$ (External)		70	ns	
t_f			18	ns	
$Q_{g(on)}$			195	nC	
Q_{gs}	$V_{GS} = 10 V$, $V_{DS} = 0.5 V_{DSS}$, $I_D = 0.5 I_{D25}$		70	nC	
Q_{gd}			64	nC	
R_{thJC}				0.18°C/W	
R_{thCK}			0.05	°C/W	

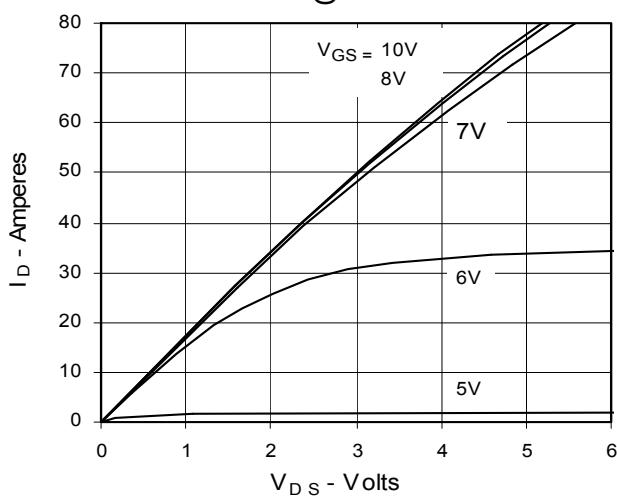
Source-Drain Diode**Characteristic Values** $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.
I_s	$V_{GS} = 0 V$		80	A
I_{SM}	Repetitive		200	A
V_{SD}	$I_F = I_s$, $V_{GS} = 0 V$, Note 1		1.5	V
t_{rr}	$I_F = 25 A$, $-di/dt = 100 A/\mu s$		200	ns
Q_{RM}	$V_R = 100 V$, $V_{GS} = 0 V$	0.8		μC
I_{RM}		8		A

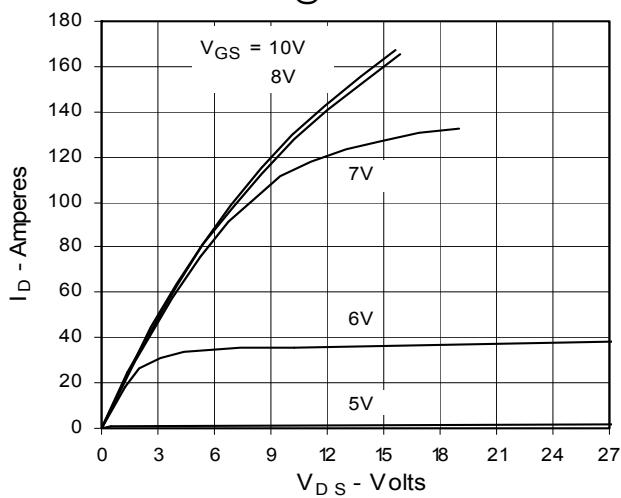
Note 1: Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2\%$ **miniBLOC, SOT-227B (IXFN) Outline**

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

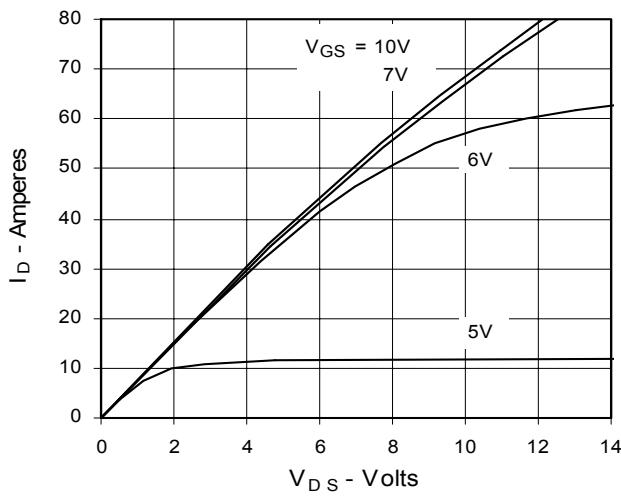
**Fig. 1. Output Characteristics
@ 25°C**



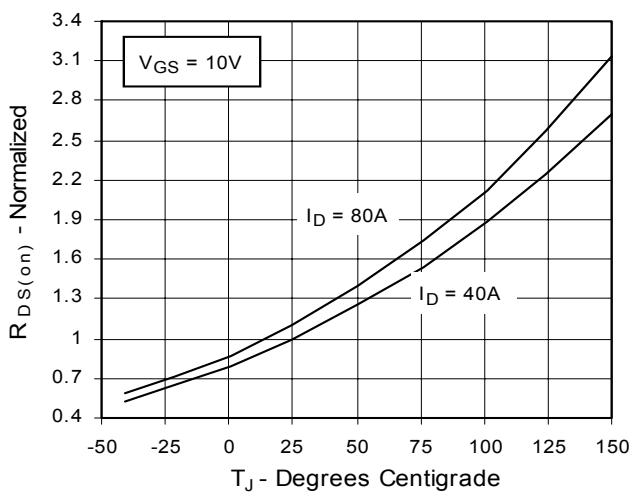
**Fig. 2. Extended Output Characteristics
@ 25°C**



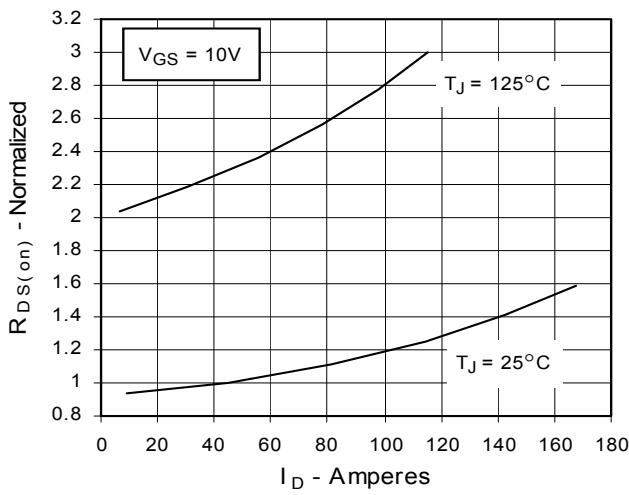
**Fig. 3. Output Characteristics
@ 125°C**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 40A$
Value vs. Junction Temperature**



**Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 40A$
Value vs. Drain Current**



**Fig. 6. Drain Current vs. Case
Temperature**

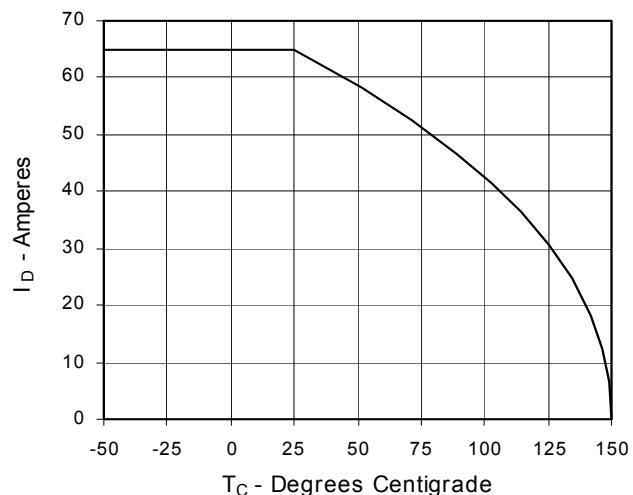


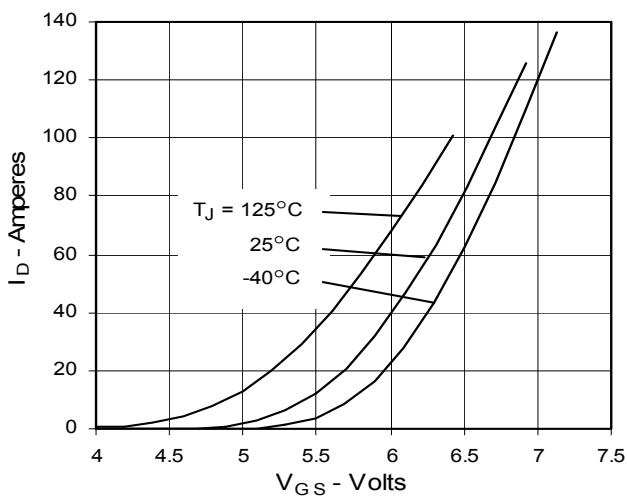
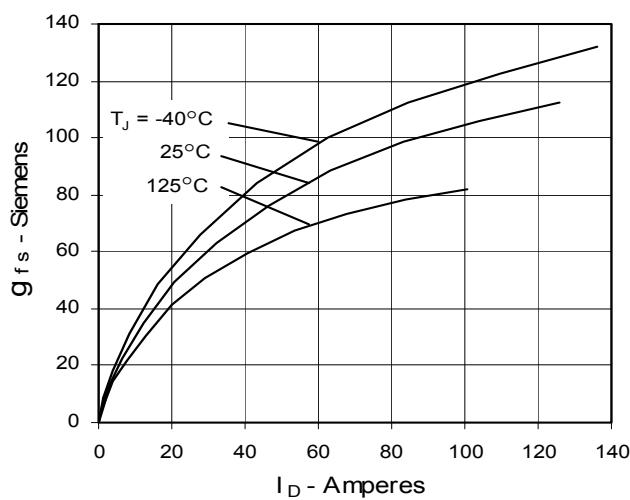
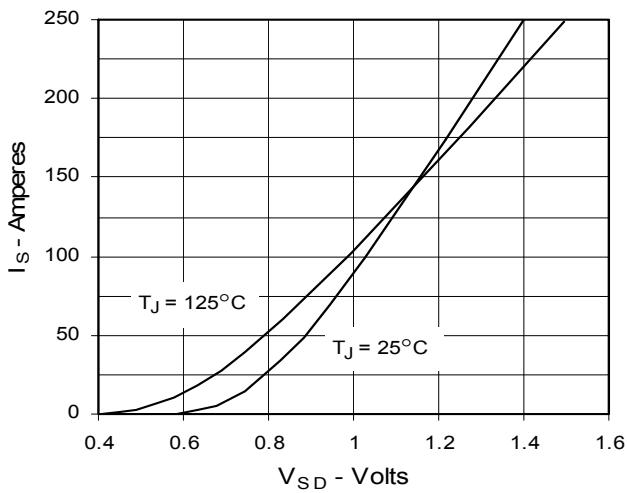
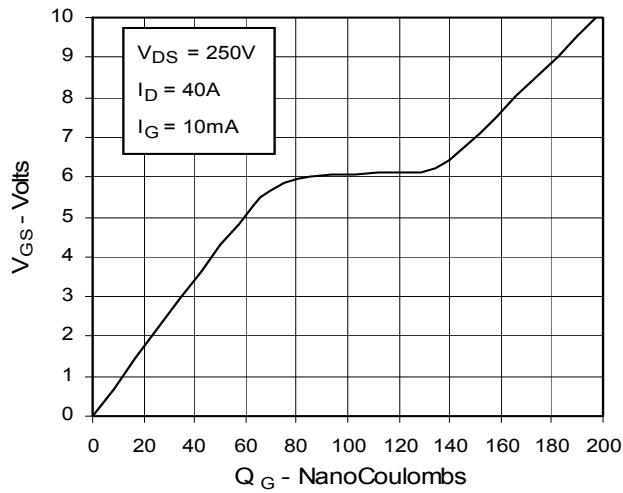
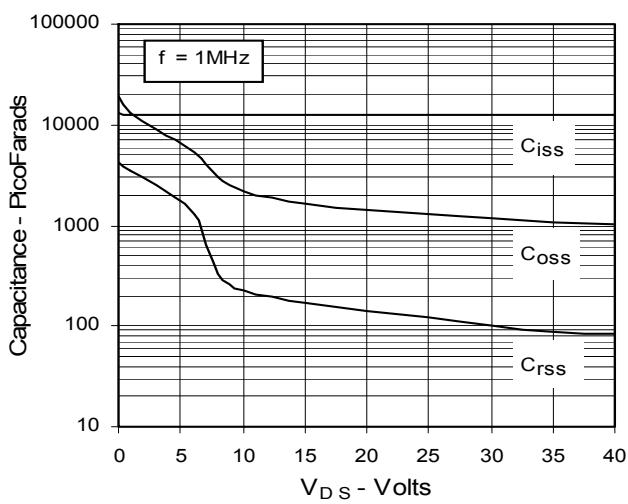
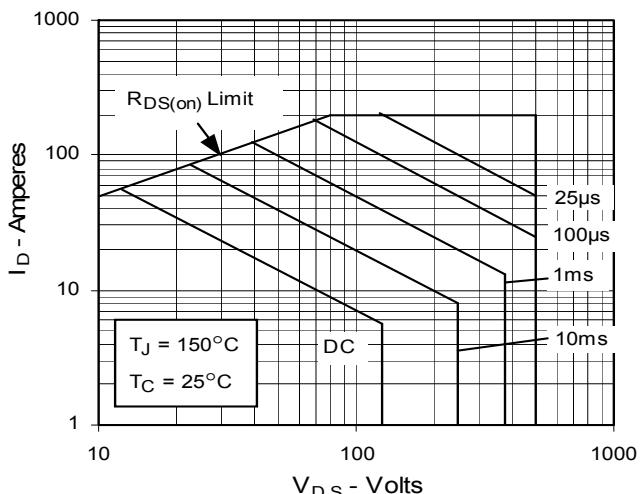
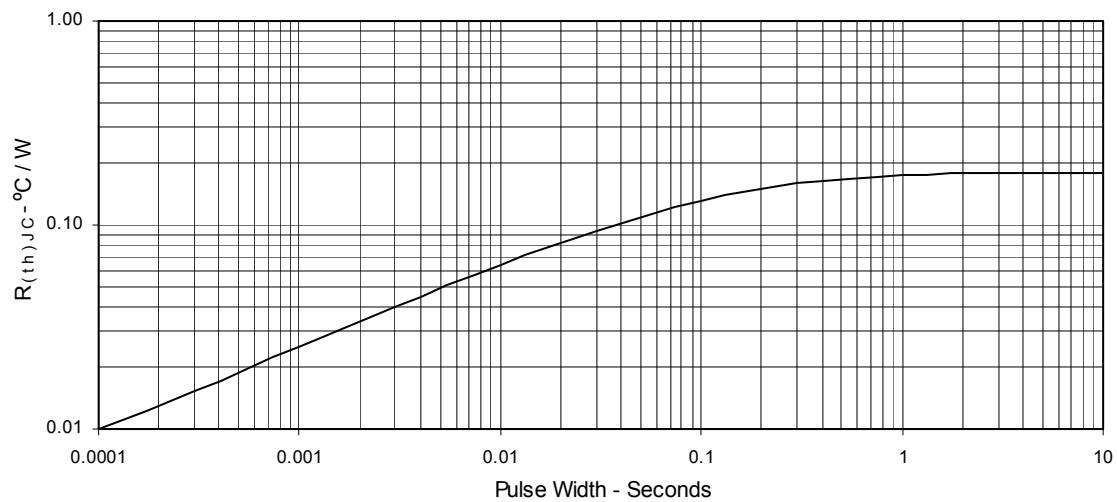
Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Source Current vs. Source-To-Drain Voltage****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Forward-Bias Safe Operating Area**

Fig. 13. Maximum Transient Thermal Resistance



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